# Silicon Epitaxial Planar Switching Diode

### Features

- Small package
- Low forward voltage
- Fast reverse recovery time
- Small total capacitance

# Applications

• Ultra high speed switching application

# Absolute Maximum Ratings (T<sub>a</sub> = 25°C)

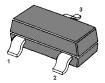
Parameter	Symbol	Value	Unit	
Maximum Peak Reverse Voltage	V <sub>RM</sub>	100	V	
Reverse Voltage	V <sub>R</sub>	75	V	
Average Forward Current		I <sub>F(AV)</sub>	200	mA
Maximum Peak Forward Current		I <sub>FM</sub>	300	mA
Non-Repetitive Peak Forward Surge Current	at t = 1 s at t = 1 μs	I <sub>FSM</sub>	1 2	А
Power Dissipation		P <sub>D</sub>	350	mW
Junction Temperature		Tj	150	C°
Storage Temperature Range		T <sub>stg</sub>	- 55 to + 150	C°

#### **Thermal Resistance**

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient <sup>1)</sup>	$R_{ ext{ hetaJA}}$	357	°C/W	

<sup>1)</sup> Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.





3

1. Anode 2. Anode 3. Cathode SOT-23 Plastic Package

# Characteristics at $T_a = 25^{\circ}C$

Parameter	Symbol	Min.	Max.	Unit
Forward Voltage				
at I <sub>F</sub> = 1 mA	V <sub>F</sub>	-	715	mV
at I <sub>F</sub> = 10 mA	V <sub>F</sub>	-	855	mV
at I <sub>F</sub> = 50 mA	V <sub>F</sub>	-	1	V
at I <sub>F</sub> = 150 mA	V <sub>F</sub>	-	1.25	V
Reverse Current				
at V <sub>R</sub> = 20 V	I <sub>R</sub>		25	nA
at V <sub>R</sub> = 75 V	I <sub>R</sub>	-	2.5	μA
at V <sub>R</sub> = 25 V, T <sub>J</sub> = 150 °C	I <sub>R</sub>	-	30	μA
at V <sub>R</sub> = 75 V, T <sub>J</sub> = 150 °C	I <sub>R</sub>	-	50	μA
Reverse Breakdown Voltage	V	75		V
at I <sub>R</sub> = 100 μA	V <sub>(BR)R</sub>	75	-	v
Total Capacitance	6		0	<b>ъ</b> Г
at $V_R = 0 V$ , f = 1 MHz	C <sub>T</sub>	-	2	pF
Reverse Recovery Time			Λ	20
at I <sub>F</sub> = 10 mA, V <sub>R</sub> = 6 V, I <sub>rr</sub> = 0.1 × I <sub>R</sub> , R <sub>L</sub> = 100 $\Omega$	t <sub>rr</sub>	-	4	ns



### **Electrical Characteristics Curves**

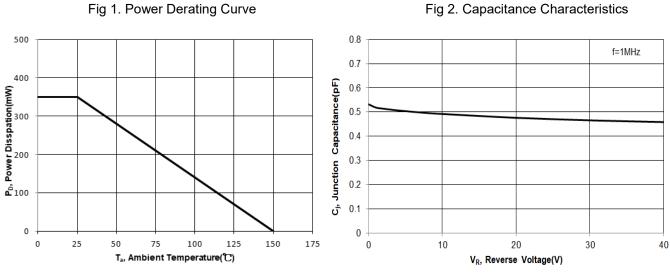


Fig 3. Reverse Characteristics

Fig 4. Forward Characteristics

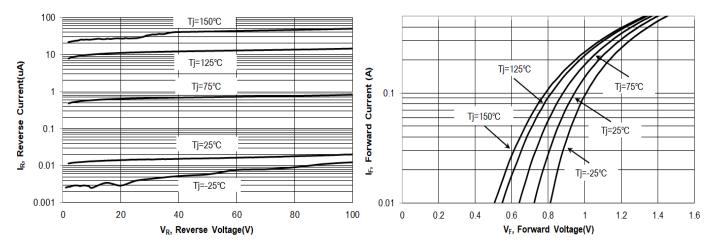
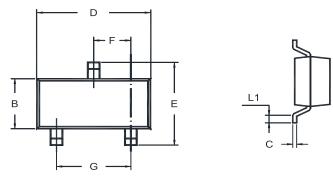
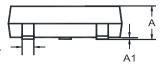




Fig 2. Capacitance Characteristics

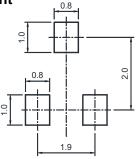
# Package Outline (Dimensions in mm)





Unit	А	A1	В	С	D	E	F	G	L	L1
	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
mm	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

# **Recommended Soldering Footprint**

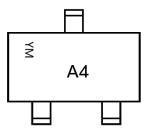


### Packing information

Tape Width		Pit	tch	Reel	Size	
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

### **Marking information**

" A4 " = Part No. "YM" = Date Code Marking "Y" = Year "M" = Month Font type: Arial



Disclaimer: Our company reserve the right to make modifications, enhancements, improvements, corrections or other changes to improve product design, functions and reliability, anytime without notice. Semtech Electronics Limited makes no warranties, representations or warranties regarding the suitability of its products for any particular purpose, and does not accept any liability arising from the application or use of any product or circuit such as: Apply to medical, military, aircraft, space or life support equipment and expressly waive any and all liability, including but not limited to special, consequential or collateral damage.



**SOT-23**